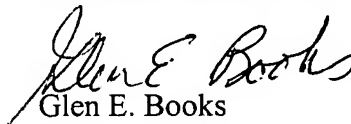


REMARKS

The specification has been amended to correct a typographical error in the priority patent 5,772,905 and to provide filing particulars on the application leading to 5,772,905.

Claim 1 has been amended to correct inadvertent typographical errors. It is clear from the specification and drawings that a mold is provided and that the film is deposited on a substrate. The mold is then urged into the film on the substrate. As shown in Fig. 1A, the release material 17 is bonded to at least a portion of the protruding features 16 and at least a portion of a recess between them.

Respectfully submitted,

A handwritten signature in cursive script, appearing to read "Glen E. Books".

Glen E. Books

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the improvement [comprising] wherein at least a portion of said protruding feature and a portion of said [release] recess have bonded thereto a release material comprising an inorganic linking group bonded to a molecular chain having release properties.

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION

After the Title on p. 1, section entitled Related Applications:

--This application is a divisional of U.S. Patent Application Serial No. 09/107,006, filed June 30, 1998, which claims priority to U.S. Patent Nos. [6]5,772,905, issued June 30, 1998 from application Serial No. 08/558,809 filed November 15, 1995.--

IN THE CLAIMS

Claim 1:

1. In a [A] lithographic method for forming a pattern in a film carried on a substrate, comprising the steps of:

[depositing a film on a substrate to provide] providing a mold having a protruding feature and a recess formed thereby, the feature and the recess having a shape forming a mold pattern;

depositing a film on a substrate;

urging the mold into the film whereby the thickness of the film under the protruding feature is reduced and a thin region is formed in the film;

removing the mold from the film;

processing the relief whereby the thin region is removed exposing a portion of the surface of the substrate which underlies the thin region; and

whereby the exposed portion of the surface of the substrate substantially replicates the mold pattern,